

Initial Product/Process Change Notification Document #:IPCN25678X Issue Date:27 Sep 2023

Title of Change:	Wafer FAB site transfer of HDG4D, HDG4 and HDG4DA Technology from BK6 Korea and Diodes, Maine, United to CZ4 Czech Republic	
Proposed First Ship date:	26 Apr 2024 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office or <u>Sungdae.Shin@onsemi.com</u> or <u>Cindy.Hong@onsemi.com</u>	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < <u>PCN.Support@onsemi.com</u> >	
Marking of Parts/ Traceability of Change:	Material will be traceable with onsemi lot trace code & date code.	
Change Category:	Wafer Fab Change	
Change Sub-Category(s):	Manufacturing Site Transfer	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Roznov, Czech Republic	None	
Description and Purpose:		

This IPCN is to notify customers of onsemi's intent to transfer the HDG4D, HDG4 and HDG4DA technology to onsemi CZ4 Czech Republic to increase wafer loading capacity.

FAB Site	Before	After
Gate Driver	onsemi Bucheon, Korea	onsemi Roznov, Czech Republic
HDG4D/HDG4DA/HDG4	Diodes, Maine, United States	

onsemi wishes to promptly inform our customer of our intent to transfer this portion of our portfolio so that you may plan appropriately and effectively for this change.

"There are no product material changes as a result of this change"

onsemi

Qualification Plan:

QV DEVICE NAME: FAN7380MX RMS 87670 PACKAGE: SOIC8

Test	Specification	Condition	Interval
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008hrs
Preconditioning	J-STD-020 JESD-A113	MSL1 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 сус
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Physical Dimensions	JESD22-B120		

QV DEVICE NAME: FAN7391MX RMS 87671 PACKAGE: SOIC14

Test	Specification	Condition	Interval
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008hrs
Preconditioning	J-STD-020 JESD-A113	MSL1 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Physical Dimensions	JESD22-B120		

QV DEVICE NAME: FSB50550BB (QV4) RMS: U89296 PACKAGE: SPM5

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008hrs
Preconditioning	J-STD-020 JESD-A113	MSL3 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -40°C to +125°C	200 сус



QV DEVICE NAME: FSB70250 (QV14) RMS: K89300 PACKAGE: SPM7

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008hrs
Preconditioning	J-STD-020 JESD-A113	MSL3 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -40°C to +125°C	1000 сус

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Qualification Vehicle
FAN7380MX, FAN7391MX, FSB70250
FAN7380MX, FAN7391MX, FSB70250
FAN7380MX, FAN7391MX, FSB70250
FAN7380MX, FAN7391MX, FSB50550BB
FAN7380MX, FAN7391MX
FAN7380MX, FAN7391MX, FSB50550BB



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FSB50550ASE	FAN7380MX, FAN7391MX, FSB50550BB
FSB50550AS	FAN7380MX, FAN7391MX, FSB50550BB
FSB50550AB	FAN7380MX, FAN7391MX, FSB50550BB
FSB50450US	FAN7380MX, FAN7391MX, FSB50550BB
FNB40560	FAN7380MX, FAN7391MX, FSB50550BB
FNB41060	FAN7380MX, FAN7391MX, FSB50550BB
FNB41060B2	FAN7380MX, FAN7391MX, FSB50550BB
FNB41560	FAN7380MX, FAN7391MX, FSB50550BB
FNB41560B2	FAN7380MX, FAN7391MX, FSB50550BB
FNB43060T2	FAN7380MX, FAN7391MX, FSB50550BB
FNC42060F	FAN7380MX, FAN7391MX, FSB50550BB
FNC42060F2	FAN7380MX, FAN7391MX, FSB50550BB
FNC42060F5	FAN7380MX, FAN7391MX, FSB50550BB
FNC42060F7V	FAN7380MX, FAN7391MX, FSB50550BB
FND43060T2	FAN7380MX, FAN7391MX, FSB50550BB
FPAM30LH60	FAN7380MX, FAN7391MX, FSB50550BB
FSB50250AP	FAN7380MX, FAN7391MX, FSB50550BB
FSB50250AS	FAN7380MX, FAN7391MX, FSB50550BB
FSB50450AS	FAN7380MX, FAN7391MX, FSB50550BB
FSB50450S	FAN7380MX, FAN7391MX, FSB50550BB
FSB50325AP	FAN7380MX, FAN7391MX, FSB50550BB
FSB50250US	FAN7380MX, FAN7391MX, FSB50550BB
FSB50250BS	FAN7380MX, FAN7391MX, FSB50550BB
FSB50250AT	FAN7380MX, FAN7391MX, FSB50550BB
FNA41560T2	FAN7380MX, FAN7391MX, FSB50550BB
FNA41560B5	FAN7380MX, FAN7391MX, FSB50550BB
FNA41560B2	FAN7380MX, FAN7391MX, FSB50550BB
FNA41560	FAN7380MX, FAN7391MX, FSB50550BB
FNA41060B7V	FAN7380MX, FAN7391MX, FSB50550BB
FAN7842MX	FAN7380MX, FAN7391MX
FAN7382MX	FAN7380MX, FAN7391MX
FAN7382M1X	FAN7380MX, FAN7391MX
FAN7380MX	FAN7380MX, FAN7391MX